

2800 JC0726'd PCT/PTO 24/AUG 2001

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Hiroji AGA et al.

Application No.: 09/857,803

Docket No.: 109725

Filed: June 11, 2001

For: METHOD FOR PRODUCING SOI WAFER AND SOI WAFER

REQUEST FOR CORRECTION OF PALM RECORDS

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

Attached is a photocopy of the original filing receipt on which errors have been corrected in red. These errors are being brought to the attention of the Patent and Trademark Office so that it may correct its records.

Respectfully submitted,

William P. Berridge
Registration No. 30,411

Joel S. Armstrong
Registration No. 36,430

WPB:JSA/cmm

Date: August 24, 2001

OLIFF & BERRIDGE, PLC
P.O. Box 19928
Alexandria, Virginia 22320
Telephone: (703) 836-6400

DEPOSIT ACCOUNT USE
AUTHORIZATION
Please grant any extension
necessary for entry;
Charge any fee due to our
Deposit Account No. 15-0461



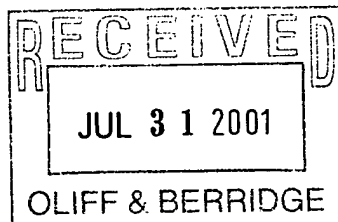
UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231
www.uspto.gov

APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/857,803	06/11/2001	2811	860	109725	4	9	3

CONFIRMATION NO. 2312

Oliff & Berridge
PO Box 19928
Alexandria, VA 22320



FILING RECEIPT



OC000000006359919

Date Mailed: 07/30/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Hiroji Aga, Gunma, JAPAN;
Naoto Tate, Gunma, JAPAN;
Susumu Kuwabara, Gunma, JAPAN;
Kiyoshi Mitani, Gunma, JAPAN;

Domestic Priority data as claimed by applicant

THIS APPLICATION IS A 371 OF PCT/JP00/07111 10/13/2000

Foreign Applications

JAPAN 11-292134 10/14/1999

Projected Publication Date: N/A

Non-Publication Request: No

Early Publication Request: No

Title

Method For Producing Soi Wafer, and Soi Wafer

~~Method for manufacturing soi wafer, and soi wafer~~

Preliminary Class

257

RECEIVED
JUL 31 2001
TC 2000 MAIL ROOM